# **100V N-CHANNEL ENHANCEMENT MODE MOSFET**

# **SUMMARY**

 $V_{(BR)DSS}$ = 100V;  $R_{DS(ON)}$ = 1 $\Omega$   $I_D$ = 0.64A

## **DESCRIPTION**

This new generation of TRENCH MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



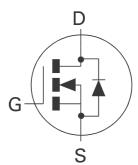
SOT23

### **FEATURES**

- Low on-resistance
- · Fast switching speed
- · Low threshold
- Low gate drive
- SOT23 package

## **APPLICATIONS**

- DC DC Converters
- Power Management Functions
- Relay and Solenoid driving
- Motor control

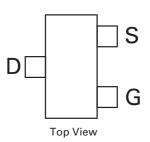


# **ORDERING INFORMATION**

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMN10A07FTA	7″	8mm	3000 units
ZXMN10A07FTC	13"	8mm	10000 units

## **DEVICE MARKING**

• 7N1





### **ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DSS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current $V_{GS}=10V$ ; $T_A=25^{\circ}C(b)$ $V_{GS}=10V$ ; $T_A=70^{\circ}C(b)$ $V_{GS}=10V$ ; $T_A=25^{\circ}C(a)$	ID	0.64 0.51 0.56	А
Pulsed Drain Current (c)	I <sub>DM</sub>	2.5	Α
Continuous Source Current (Body Diode) (b)	IS	2	Α
Pulsed Source Current (Body Diode)(c)	I <sub>SM</sub>	2.5	Α
Power Dissipation at T <sub>A</sub> =25°C (a) Linear Derating Factor	PD	625 5	mW mW/°C
Power Dissipation at T <sub>A</sub> =25°C (b) Linear Derating Factor	PD	806 6.4	mW mW/°C
Operating and Storage Temperature Range	T <sub>j</sub> :T <sub>stg</sub>	-55 to +150	°C

## THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	200	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	155	°C/W

## NOTES

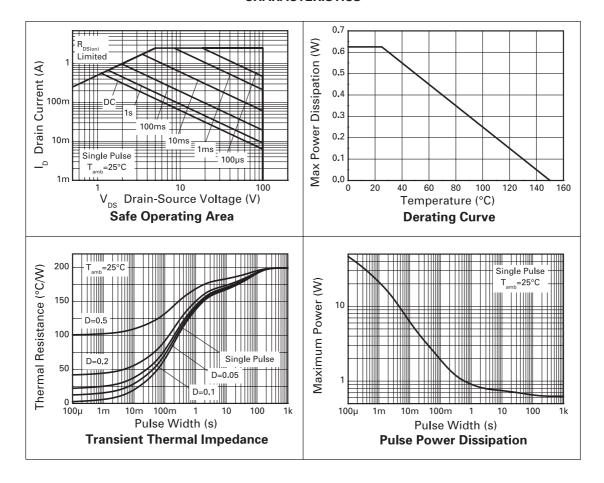


<sup>(</sup>a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

<sup>(</sup>b) For a device surface mounted on FR4 PCB measured at t≤5 secs.

<sup>(</sup>c) Repetitive rating 25mm x 25mm FR4 PCB, D=0.05, pulse width 10µs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

### **CHARACTERISTICS**





## **ELECTRICAL CHARACTERISTICS** (at TA = 25°C unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.	
STATIC					•		
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	100			V	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	
Gate-Body Leakage	IGSS			100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	2.0		4.0	V	I <sub>D</sub> =250μA, V <sub>DS</sub> = V <sub>GS</sub>	
Static Drain-Source On-State Resistance (1)	R <sub>DS(on)</sub>			1 1.1	$\Omega$	V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A V <sub>GS</sub> =6V, I <sub>D</sub> =1A	
Forward Transconductance (3)	9fs		1.6		S	V <sub>DS</sub> =15V,I <sub>D</sub> =1A	
DYNAMIC (3)							
Input Capacitance	C <sub>iss</sub>		138		pF		
Output Capacitance	Coss		12		pF	V <sub>DS</sub> =60 V, V <sub>GS</sub> =0V, f=1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		6		pF		
SWITCHING(2) (3)							
Turn-On Delay Time	t <sub>d(on)</sub>		1.8		ns		
Rise Time	t <sub>r</sub>		1.5		ns	V <sub>DD</sub> =50V, I <sub>D</sub> =1A	
Turn-Off Delay Time	t <sub>d(off)</sub>		4.1		ns	$R_{G}=6.0\Omega$ , $V_{GS}=10V$	
Fall Time	t <sub>f</sub>		2.1		ns		
Total Gate Charge	Qg		2.9		nC	V <sub>DS</sub> =50V,V <sub>GS</sub> =10V, I <sub>D</sub> =1.0A	
Gate-Source Charge	Qgs		0.7		nC		
Gate-Drain Charge	Q <sub>gd</sub>		1		nC		
SOURCE-DRAIN DIODE							
Diode Forward Voltage (1)	V <sub>SD</sub>			0.95	V	TJ=25°C, IS=1.5A, VGS=0V	
Reverse Recovery Time (3)	t <sub>rr</sub>		27		ns	T <sub>J</sub> =25°C, I <sub>F</sub> =1.8A, di/dt= 100A/μs	
Reverse Recovery Charge (3)	Q <sub>rr</sub>		12		nC		

#### NOTES

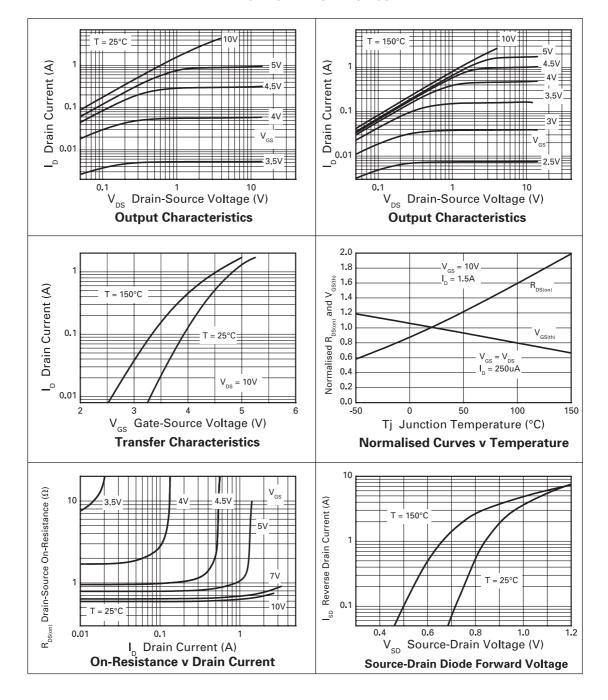


<sup>(1)</sup> Measured under pulsed conditions. Width≤300µs. Duty cycle  $\leq~2\%$  .

<sup>(2)</sup> Switching characteristics are independent of operating junction temperature.

<sup>(3)</sup> For design aid only, not subject to production testing.

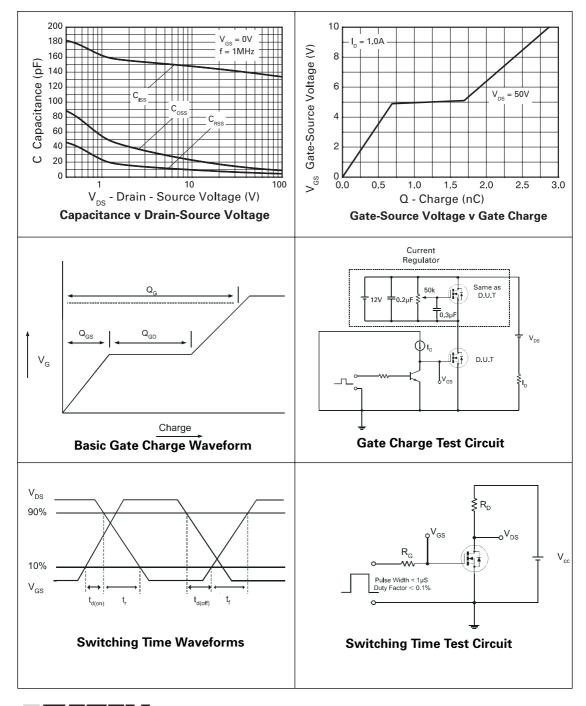
### **TYPICAL CHARACTERISTICS**



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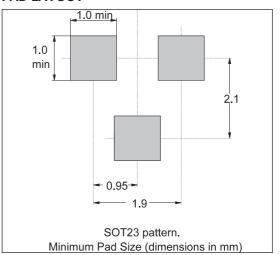
## **TYPICAL CHARACTERISTICS**





### **PACKAGE OUTLINE**

### **PAD LAYOUT**



#### **PACKAGE DIMENSIONS**

DIM	MILLIN	MILLIMETRES		MILLIMETRES		
I DIIVI	MIN	MAX	DIM	MIN	MAX	
Α	2.67	3.05	Н	0.33	0.51	
В	1.20	1.40	K	0.01	0.10	
С	_	1.10	L	2.10	2.50	
D	0.37	0.53	М	0.45	0.64	
F	0.085	0.15	N	0.95 NOM		
G	1.90 NOM		φ	10° TYP		

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